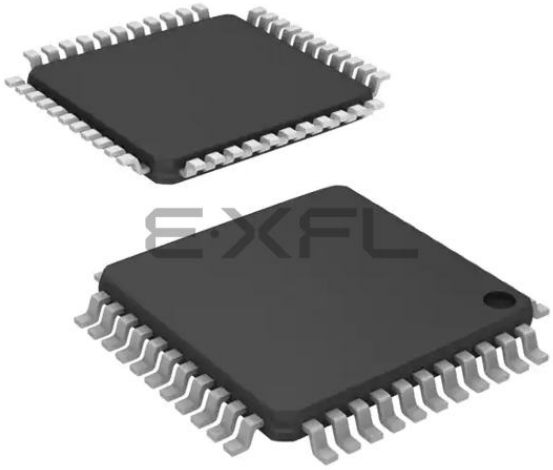

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	CANbus, I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	80KB (40K x 16)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	3.25K x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 11x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f4682-e-pt

TABLE 1-2: PIC18F2682/2685 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number PDIP, SOIC	Pin Type	Buffer Type	Description
				PORTA is a bidirectional I/O port.
RA0/AN0	2			
RA0		I/O	TTL	Digital I/O.
AN0		I	Analog	Analog input 0.
RA1/AN1	3			
RA1		I/O	TTL	Digital I/O.
AN1		I	Analog	Analog input 1.
RA2/AN2/VREF-	4			
RA2		I/O	TTL	Digital I/O.
AN2		I	Analog	Analog input 2.
VREF-		I	Analog	A/D reference voltage (low) input.
RA3/AN3/VREF+	5			
RA3		I/O	TTL	Digital I/O.
AN3		I	Analog	Analog input 3.
VREF+		I	Analog	A/D reference voltage (high) input.
RA4/T0CKI	6			
RA4		I/O	TTL	Digital I/O.
T0CKI		I	ST	Timer0 external clock input.
RA5/AN4/$\overline{SS}$/HLVDIN	7			
RA5		I/O	TTL	Digital I/O.
AN4		I	Analog	Analog input 4.
$\overline{SS}$		I	TTL	SPI slave select input.
HLVDIN		I	Analog	High/Low-Voltage Detect input.
RA6				See the OSC2/CLKO/RA6 pin.
RA7				See the OSC1/CLKI/RA7 pin.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power

2.0 OSCILLATOR CONFIGURATIONS

2.1 Oscillator Types

PIC18F2682/2685/4682/4685 devices can be operated in ten different oscillator modes. The user can program the Configuration bits, FOSC3:FOSC0, in Configuration Register 1H to select one of these ten modes:

1. LP Low-Power Crystal
2. XT Crystal/Resonator
3. HS High-Speed Crystal/Resonator
4. HSPLL High-Speed Crystal/Resonator with PLL enabled
5. RC External Resistor/Capacitor with FOSC/4 output on RA6
6. RCIO External Resistor/Capacitor with I/O on RA6
7. INTIO1 Internal Oscillator with FOSC/4 output on RA6 and I/O on RA7
8. INTIO2 Internal Oscillator with I/O on RA6 and RA7
9. EC External Clock with FOSC/4 output
10. ECIO External Clock with I/O on RA6

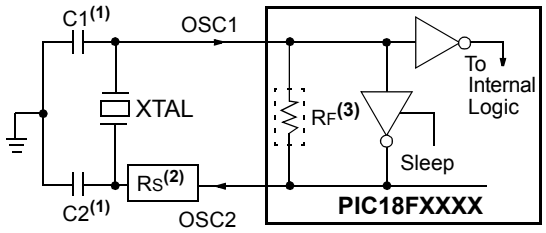
2.2 Crystal Oscillator/Ceramic Resonators

In XT, LP, HS or HSPLL Oscillator modes, a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation. Figure 2-1 shows the pin connections.

The oscillator design requires the use of a parallel cut crystal.

Note:	Use of a series cut crystal may give a frequency out of the crystal manufacturer's specifications.

FIGURE 2-1: CRYSTAL/CERAMIC RESONATOR OPERATION (XT, LP, HS OR HSPLL CONFIGURATION)



Note 1: See Table 2-1 and Table 2-2 for initial values of C1 and C2.
2: A series resistor (RS) may be required for AT strip cut crystals.
3: RF varies with the oscillator mode chosen.

TABLE 2-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Typical Capacitor Values Used:			
Mode	**Freq**	**OSC1**	**OSC2**
XT	455 kHz 2.0 MHz 4.0 MHz	56 pF 47 pF 33 pF	56 pF 47 pF 33 pF
HS	8.0 MHz 16.0 MHz	27 pF 22 pF	27 pF 22 pF

Capacitor values are for design guidance only.

These capacitors were tested with the resonators listed below for basic start-up and operation. **These values are not optimized**.

Different capacitor values may be required to produce acceptable oscillator operation. The user should test the performance of the oscillator over the expected VDD and temperature range for the application.

See the notes on page 26 for additional information.

Resonators Used:	
455 kHz	4.0 MHz
2.0 MHz	8.0 MHz
16.0 MHz	

Note:	When using resonators with frequencies above 3.5 MHz, the use of HS mode, rather than XT mode, is recommended. HS mode may be used at any VDD for which the controller is rated. If HS is selected, it is possible that the gain of the oscillator will overdrive the resonator. Therefore, a series resistor should be placed between the OSC2 pin and the resonator. As a good starting point, the recommended value of RS is 330Ω.

3.4.3 RC_IDLE MODE

In RC_IDLE mode, the CPU is disabled but the peripherals continue to be clocked from the internal oscillator block using the INTOSC multiplexer. This mode allows for controllable power conservation during Idle periods.

From RC_RUN, this mode is entered by setting the IDLEN bit and executing a SLEEP instruction. If the device is in another Run mode, first set IDLEN, then set the SCS1 bit and execute SLEEP. Although its value is ignored, it is recommended that SCS0 also be cleared; this is to maintain software compatibility with future devices. The INTOSC multiplexer may be used to select a higher clock frequency, by modifying the IRCF bits, before executing the SLEEP instruction. When the clock source is switched to the INTOSC multiplexer, the primary oscillator is shut down and the OSTS bit is cleared.

If the IRCF bits are set to any non-zero value or the INTSRC bit is set, the INTOSC output is enabled. The IOFS bit becomes set, after the INTOSC output becomes stable, after an interval of TIOBST (parameter 39, Table 27-10). Clocks to the peripherals continue while the INTOSC source stabilizes. If the IRCF bits were previously at a non-zero value, or INTSRC was set before the SLEEP instruction was executed and the INTOSC source was already stable, the IOFS bit will remain set. If the IRCF bits and INTSRC are all clear, the INTOSC output will not be enabled, the IOFS bit will remain clear and there will be no indication of the current clock source.

When a wake event occurs, the peripherals continue to be clocked from the INTOSC multiplexer. After a delay of TCSD following the wake event, the CPU begins executing code being clocked by the INTOSC multiplexer. The IDLEN and SCS bits are not affected by the wake-up. The INTRC source will continue to run if either the WDT or the Fail-Safe Clock Monitor is enabled.

3.5 Exiting Idle and Sleep Modes

An exit from Sleep mode or any of the Idle modes is triggered by an interrupt, a Reset or a WDT time-out. This section discusses the triggers that cause exits from power-managed modes. The clocking subsystem actions are discussed in each of the power-managed modes (see **Section 3.2 “Run Modes”, Section 3.3 “Sleep Mode”** and **Section 3.4 “Idle Modes”**).

3.5.1 EXIT BY INTERRUPT

Any of the available interrupt sources can cause the device to exit from an Idle mode or the Sleep mode to a Run mode. To enable this functionality, an interrupt source must be enabled by setting its enable bit in one of the INTCON or PIE registers. The exit sequence is initiated when the corresponding interrupt flag bit is set.

On all exits from Idle or Sleep modes by interrupt, code execution branches to the interrupt vector if the GIE/GIEH bit (INTCON<7>) is set. Otherwise, code execution continues or resumes without branching (see **Section 9.0 “Interrupts”**).

A fixed delay of interval TCSD following the wake event is required when leaving the Sleep and Idle modes. This delay is required for the CPU to prepare for execution. Instruction execution resumes on the first clock cycle following this delay.

3.5.2 EXIT BY WDT TIME-OUT

A WDT time-out will cause different actions depending on which power-managed mode the device is in when the time-out occurs.

If the device is not executing code (all Idle modes and Sleep mode), the time-out will result in an exit from the power-managed mode (see **Section 3.2 “Run Modes”** and **Section 3.3 “Sleep Mode”**). If the device is executing code (all Run modes), the time-out will result in a WDT Reset (see **Section 24.2 “Watchdog Timer (WDT)”**).

The WDT timer and postscaler are cleared by executing a SLEEP or CLRWDT instruction, the loss of a currently selected clock source (if the Fail-Safe Clock Monitor is enabled) and modifying the IRCF bits in the OSCCON register if the internal oscillator block is the device clock source.

3.5.3 EXIT BY RESET

Normally, the device is held in Reset by the Oscillator Start-up Timer (OST) until the primary clock becomes ready. At that time, the OSTS bit is set and the device begins executing code. If the internal oscillator block is the new clock source, the IOFS bit is set instead.

The exit delay time from Reset to the start of code execution depends on both the clock sources before and after the wake-up and the type of oscillator if the new clock source is the primary clock. Exit delays are summarized in Table 3-2.

Code execution can begin before the primary clock becomes ready. If either the Two-Speed Start-up (see **Section 24.3 “Two-Speed Start-up”**) or Fail-Safe Clock Monitor (see **Section 24.4 “Fail-Safe Clock Monitor”**) is enabled, the device may begin execution as soon as the Reset source has cleared. Execution is clocked by the INTOSC multiplexer driven by the internal oscillator block. Execution is clocked by the internal oscillator block until either the primary clock becomes ready or a power-managed mode is entered before the primary clock becomes ready; the primary clock is then shut down.

TABLE 4-4: INITIALIZATION CONDITIONS FOR ALL REGISTERS (CONTINUED)

Register	Applicable Devices				Power-on Reset, Brown-out Reset	$\overline{\text{MCLR}}$ Resets, WDT Reset, RESET Instruction, Stack Resets	Wake-up via WDT or Interrupt
PIR2	2682	2685	4682	4685	00-0 0000	00-0 0000	uu-u uuuu(1)
	2682	2685	4682	4685	0--0 000-	0--0 000-	u--u uuu-(1)
PIE2	2682	2685	4682	4685	00-0 0000	00-0 0000	uu-u uuuu
	2682	2685	4682	4685	0--0 000-	0--0 000-	u--u uuu-
IPR1	2682	2685	4682	4685	1111 1111	1111 1111	uuuu uuuu
	2682	2685	4682	4685	-111 1111	-111 1111	-uuu uuuu
PIR1	2682	2685	4682	4685	0000 0000	0000 0000	uuuu uuuu(1)
	2682	2685	4682	4685	-000 0000	-000 0000	-uuu uuuu
PIE1	2682	2685	4682	4685	0000 0000	0000 0000	uuuu uuuu
	2682	2685	4682	4685	-000 0000	-000 0000	-uuu uuuu
OSCTUNE	2682	2685	4682	4685	0q-0 0000	0q-0 0000	uu-u uuuu
TRISE	2682	2685	4682	4685	0000 -111	0000 -111	uuuu -uuu
TRISD	2682	2685	4682	4685	1111 1111	1111 1111	uuuu uuuu
TRISC	2682	2685	4682	4685	1111 1111	1111 1111	uuuu uuuu
TRISB	2682	2685	4682	4685	1111 1111	1111 1111	uuuu uuuu
TRISA(5)	2682	2685	4682	4685	1111 1111(5)	1111 1111(5)	uuuu uuuu(5)
LATE	2682	2685	4682	4685	---- -xxx	---- -uuu	---- -uuu
LATD	2682	2685	4682	4685	xxxx xxxx	uuuu uuuu	uuuu uuuu
LATC	2682	2685	4682	4685	xxxx xxxx	uuuu uuuu	uuuu uuuu
LATB	2682	2685	4682	4685	xxxx xxxx	uuuu uuuu	uuuu uuuu
LATA(5)	2682	2685	4682	4685	xxxx xxxx(5)	uuuu uuuu(5)	uuuu uuuu(5)
PORTE	2682	2685	4682	4685	---- x000	---- x000	---- uuuu
PORTD	2682	2685	4682	4685	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTC	2682	2685	4682	4685	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTB	2682	2685	4682	4685	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA(5)	2682	2685	4682	4685	xx0x 0000(5)	uu0u 0000(5)	uuuu uuuu(5)
ECANCON	2682	2685	4682	4685	0001 0000	0001 0000	uuuu uuuu
TXERRCNT	2682	2685	4682	4685	0000 0000	0000 0000	uuuu uuuu
RXERRCNT	2682	2685	4682	4685	0000 0000	0000 0000	uuuu uuuu
COMSTAT	2682	2685	4682	4685	0000 0000	0000 0000	uuuu uuuu
CIOCON	2682	2685	4682	4685	--00 ----	--00 ----	--uu ----

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition. Shaded cells indicate conditions do not apply for the designated device.

Note 1: One or more bits in the INTCONx or PIRx registers will be affected (to cause wake-up).

2: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the PC is loaded with the interrupt vector (0008h or 0018h).

3: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the TOSU, TOSH and TOSL are updated with the current value of the PC. The STKPTR is modified to point to the next location in the hardware stack.

4: See Table 4-3 for Reset value for specific condition.

5: Bits 6 and 7 of PORTA, LATA and TRISA are enabled depending on the oscillator mode selected. When not enabled as PORTA pins, they are disabled and read '0'.

6: This register reads all '0's until the ECAN™ technology is set up in Mode 1 or Mode 2.

7.6 Operation During Code-Protect

Data EEPROM memory has its own code-protect bits in Configuration Words. External read and write operations are disabled if code protection is enabled.

The microcontroller itself can both read and write to the internal Data EEPROM, regardless of the state of the code-protect Configuration bit. Refer to **Section 24.0 "Special Features of the CPU"** for additional information.

7.7 Protection Against Spurious Write

There are conditions when the device may not want to write to the data EEPROM memory. To protect against spurious EEPROM writes, various mechanisms have been implemented. On power-up, the WREN bit is cleared. In addition, writes to the EEPROM are blocked during the Power-up Timer period (TPWRT, parameter 33).

The write initiate sequence and the WREN bit together help prevent an accidental write during brown-out, power glitch or software malfunction.

7.8 Using the Data EEPROM

The data EEPROM is a high-endurance, byte address-able array that has been optimized for the storage of frequently changing information (e.g., program variables or other data that are updated often). Frequently changing values will typically be updated more often than specification D124. If this is not the case, an array refresh must be performed. For this reason, variables that change infrequently (such as constants, IDs, calibration, etc.) should be stored in Flash program memory.

A simple data EEPROM refresh routine is shown in Example 7-3.

Note:	If data EEPROM is only used to store constants and/or data that changes rarely, an array refresh is likely not required. See specification D124.

EXAMPLE 7-3: DATA EEPROM REFRESH ROUTINE

```
        CLRF    EEADR               ; Start at address 0
        CLRF    EEADRH              ;
        BCF     EECON1, CFGS        ; Set for memory
        BCF     EECON1, EEPGD       ; Set for Data EEPROM
        BCF     INTCON, GIE         ; Disable interrupts
        BSF     EECON1, WREN        ; Enable writes
Loop                                ; Loop to refresh array
        BSF     EECON1, RD          ; Read current address
        MOVLW   55h                 ;
        MOVWF   EECON2              ; Write 55h
        MOVLW   0AAh                ;
        MOVWF   EECON2              ; Write 0AAh
        BSF     EECON1, WR          ; Set WR bit to begin write
        BTFSC   EECON1, WR          ; Wait for write to complete
        BRA     $-2
        INCFSZ  EEADR, F            ; Increment address
        BRA     LOOP                ; Not zero, do it again
        INCFSZ  EEADRH, F           ; Increment the high address
        BRA     LOOP                ; Not zero, do it again

        BCF     EECON1, WREN        ; Disable writes
        BSF     INTCON, GIE         ; Enable interrupts
```

TABLE 10-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
PORTA	RA7(1)	RA6(1)	RA5	RA4	RA3	RA2	RA1	RA0	54
LATA	LATA7(1)	LATA6(1)	LATA Data Output Register						54
TRISA	TRISA7(1)	TRISA6(1)	PORTA Data Direction Register						54
ADCON1	—	—	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0	52
CMCON(2)	C2OUT	C1OUT	C2INV	C1INV	CIS	CM2	CM1	CM0	53
CVRCON(2)	CVREN	CVROE	CVRR	CVRSS	CVR3	CVR2	CVR1	CVR0	53

Legend: — = unimplemented, read as '0'. Shaded cells are not used by PORTA.

Note 1: RA7:RA6 and their associated latch and data direction bits are enabled as I/O pins based on oscillator configuration; otherwise, they are read as '0'.

2: These registers are unimplemented on PIC18F2682/2685 devices.

16.0 ENHANCED CAPTURE/ COMPARE/PWM (ECCP1) MODULE

Note:	The ECCP1 module is implemented only in PIC18F4682/4685 (40/44-pin) devices.

In PIC18F4682/4685 devices, ECCP1 is implemented as a standard CCP1 module with Enhanced PWM capabilities. These include the provision for 2 or 4 output channels, user-selectable polarity, dead-band control and automatic shutdown and restart. The enhanced features are discussed in detail in **Section 16.4 "Enhanced PWM Mode"**. Capture, Compare and single output PWM functions of the ECCP1 module are the same as described for the standard CCP1 module.

The control register for the Enhanced CCP1 module is shown in Register 16-1. It differs from the CCP1CON register in the PIC18F2682/2685 devices in that the two Most Significant bits are implemented to control PWM functionality.

REGISTER 16-1: ECCP1CON: ENHANCED CAPTURE/COMPARE/PWM CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
EPWM1M1	EPWM1M0	EDC1B1	EDC1B0	ECCP1M3	ECCP1M2	ECCP1M1	ECCP1M0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **EPWM1M1:EPWM1M0:** Enhanced PWM Output Configuration bits

If ECCP1M3:ECCP1M2 = 00, 01, 10:

xx = P1A assigned as Capture/Compare input/output; P1B, P1C, P1D assigned as port pins

If ECCP1M3:ECCP1M2 = 11:

00 = Single output: P1A modulated; P1B, P1C, P1D assigned as port pins
01 = Full-bridge output forward: P1D modulated; P1A active; P1B, P1C inactive
10 = Half-bridge output: P1A, P1B modulated with dead-band control; P1C, P1D assigned as port pins
11 = Full-bridge output reverse: P1B modulated; P1C active; P1A, P1D inactive

bit 5-4 **EDC1B1:EDC1B0**: ECCP1 Module PWM Duty Cycle bit 1 and bit 0

Capture mode:
Unused.

Compare mode:
Unused.

PWM mode:
These bits are the two LSbs of the 10-bit PWM duty cycle. The eight MSbs of the duty cycle are found in ECCPR1L.

bit 3-0 **ECCP1M3:ECCP1M0**: Enhanced CCP1 Mode Select bits

0000 = Capture/Compare/PWM off (resets ECCP1 module)
0001 = Reserved
0010 = Compare mode; toggle output on match
0011 = Reserved
0100 = Capture mode; every falling edge
0101 = Capture mode; every rising edge
0110 = Capture mode; every 4th rising edge
0111 = Capture mode; every 16th rising edge
1000 = Compare mode; initialize ECCP1 pin low; set output on compare match (set ECCP1IF)
1001 = Compare mode; initialize ECCP1 pin high; clear output on compare match (set ECCP1IF)
1010 = Compare mode; generate software interrupt only; ECCP1 pin reverts to I/O state
1011 = Compare mode; trigger special event (ECCP1 resets TMR1 or TMR3, sets ECCP1IF bit and starts the A/D conversion on ECCP1 match)
1100 = PWM mode; P1A, P1C active-high; P1B, P1D active-high
1101 = PWM mode; P1A, P1C active-high; P1B, P1D active-low
1110 = PWM mode; P1A, P1C active-low; P1B, P1D active-high
1111 = PWM mode; P1A, P1C active-low; P1B, P1D active-low

17.4.12 ACKNOWLEDGE SEQUENCE TIMING

An Acknowledge sequence is enabled by setting the Acknowledge sequence enable bit, ACKEN (SSPCON2<4>). When this bit is set, the SCL pin is pulled low and the contents of the Acknowledge data bit are presented on the SDA pin. If the user wishes to generate an Acknowledge, then the ACKDT bit should be cleared. If not, the user should set the ACKDT bit before starting an Acknowledge sequence. The Baud Rate Generator then counts for one rollover period (TBRG) and the SCL pin is deasserted (pulled high). When the SCL pin is sampled high (clock arbitration), the Baud Rate Generator counts for TBRG. The SCL pin is then pulled low. Following this, the ACKEN bit is automatically cleared, the Baud Rate Generator is turned off and the MSSP module then goes into Idle mode (Figure 17-23).

17.4.12.1 WCOL Status Flag

If the user writes the SSPBUF when an Acknowledge sequence is in progress, then WCOL is set and the contents of the buffer are unchanged (the write doesn't occur).

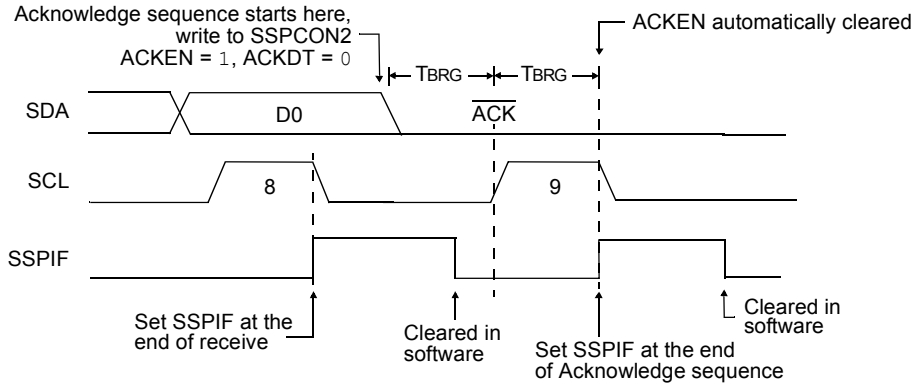
17.4.13 STOP CONDITION TIMING

A Stop bit is asserted on the SDA pin at the end of a receive/transmit by setting the Stop Sequence Enable bit, PEN (SSPCON2<2>). At the end of a receive/transmit, the SCL line is held low after the falling edge of the ninth clock. When the PEN bit is set, the master will assert the SDA line low. When the SDA line is sampled low, the Baud Rate Generator is reloaded and counts down to 0. When the Baud Rate Generator times out, the SCL pin will be brought high and one TBRG (Baud Rate Generator rollover count) later, the SDA pin will be deasserted. When the SDA pin is sampled high while SCL is high, the P bit (SSPSTAT<4>) is set. A TBRG later, the PEN bit is cleared and the SSPIF bit is set (Figure 17-24).

17.4.13.1 WCOL Status Flag

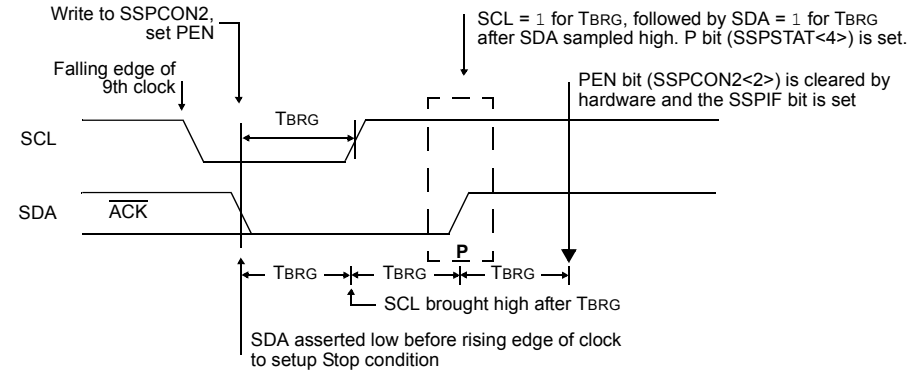
If the user writes the SSPBUF when a Stop sequence is in progress, then the WCOL bit is set and the contents of the buffer are unchanged (the write doesn't occur).

FIGURE 17-23: ACKNOWLEDGE SEQUENCE WAVEFORM



Note: TBRG = one Baud Rate Generator period.

FIGURE 17-24: STOP CONDITION RECEIVE OR TRANSMIT MODE



Note: TBRG = one Baud Rate Generator period.

TABLE 18-3: BAUD RATES FOR ASYNCHRONOUS MODES

BAUD RATE (K)	SYNC = 0, BRGH = 0, BRG16 = 0											
	FOSC = 40.000 MHz			FOSC = 20.000 MHz			FOSC = 10.000 MHz			FOSC = 8.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	—	—	—	—	—	—	—	—	—	—	—	—
1.2	—	—	—	1.221	1.73	255	1.202	0.16	129	1.201	-0.16	103
2.4	2.441	1.73	255	2.404	0.16	129	2.404	0.16	64	2.403	-0.16	51
9.6	9.615	0.16	64	9.766	1.73	31	9.766	1.73	15	9.615	-0.16	12
19.2	19.531	1.73	31	19.531	1.73	15	19.531	1.73	7	—	—	—
57.6	56.818	-1.36	10	62.500	8.51	4	52.083	-9.58	2	—	—	—
115.2	125.000	8.51	4	104.167	-9.58	2	78.125	-32.18	1	—	—	—

BAUD RATE (K)	SYNC = 0, BRGH = 0, BRG16 = 0								
	FOSC = 4.000 MHz			FOSC = 2.000 MHz			FOSC = 1.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	0.300	0.16	207	0.300	-0.16	103	0.300	-0.16	51
1.2	1.202	0.16	51	1.201	-0.16	25	1.201	-0.16	12
2.4	2.404	0.16	25	2.403	-0.16	12	—	—	—
9.6	8.929	-6.99	6	—	—	—	—	—	—
19.2	20.833	8.51	2	—	—	—	—	—	—
57.6	62.500	8.51	0	—	—	—	—	—	—
115.2	62.500	-45.75	0	—	—	—	—	—	—

BAUD RATE (K)	SYNC = 0, BRGH = 1, BRG16 = 0											
	FOSC = 40.000 MHz			FOSC = 20.000 MHz			FOSC = 10.000 MHz			FOSC = 8.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	—	—	—	—	—	—	—	—	—	—	—	—
1.2	—	—	—	—	—	—	—	—	—	—	—	—
2.4	—	—	—	—	—	—	2.441	1.73	255	2.403	-0.16	207
9.6	9.766	1.73	255	9.615	0.16	129	9.615	0.16	64	9.615	-0.16	51
19.2	19.231	0.16	129	19.231	0.16	64	19.531	1.73	31	19.230	-0.16	25
57.6	58.140	0.94	42	56.818	-1.36	21	56.818	-1.36	10	55.555	3.55	8
115.2	113.636	-1.36	21	113.636	-1.36	10	125.000	8.51	4	—	—	—

BAUD RATE (K)	SYNC = 0, BRGH = 1, BRG16 = 0								
	FOSC = 4.000 MHz			FOSC = 2.000 MHz			FOSC = 1.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	—	—	—	—	—	—	0.300	-0.16	207
1.2	1.202	0.16	207	1.201	-0.16	103	1.201	-0.16	51
2.4	2.404	0.16	103	2.403	-0.16	51	2.403	-0.16	25
9.6	9.615	0.16	25	9.615	-0.16	12	—	—	—
19.2	19.231	0.16	12	—	—	—	—	—	—
57.6	62.500	8.51	3	—	—	—	—	—	—
115.2	125.000	8.51	1	—	—	—	—	—	—

19.6 A/D Conversions

Figure 19-3 shows the operation of the A/D converter after the GO/$\overline{\text{DONE}}$ bit has been set and the ACQT2:ACQT0 bits are cleared. A conversion is started after the following instruction to allow entry into Sleep mode before the conversion begins.

Figure 19-4 shows the operation of the A/D converter after the GO/$\overline{\text{DONE}}$ bit has been set, the ACQT2:ACQT0 bits are set to '010' and a 4 TAD acquisition time is selected before the conversion starts.

Clearing the GO/$\overline{\text{DONE}}$ bit during a conversion will abort the current conversion. The A/D Result register pair will NOT be updated with the partially completed A/D conversion sample. This means the ADRESH:ADRESL registers will continue to contain the value of the last completed conversion (or the last value written to the ADRESH:ADRESL registers).

After the A/D conversion is completed or aborted, a 2 TAD wait is required before the next acquisition can be started. After this wait, acquisition on the selected channel is automatically started.

Note:	The GO/$\overline{\text{DONE}}$ bit should **NOT** be set in the same instruction that turns on the A/D.

FIGURE 19-3: A/D CONVERSION TAD CYCLES (ACQT<2:0> = 000, TACQ = 0)

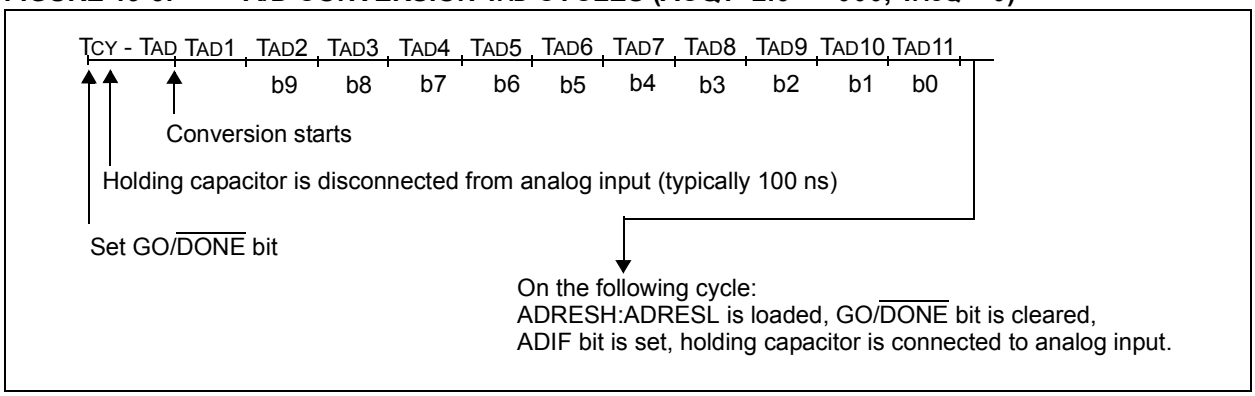
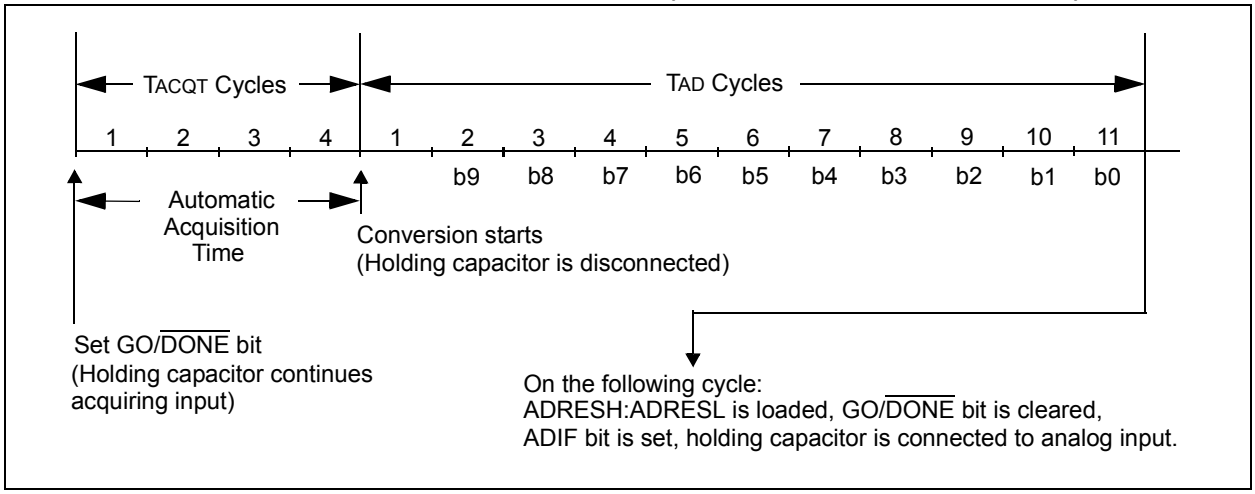


FIGURE 19-4: A/D CONVERSION TAD CYCLES (ACQT<2:0> = 010, TACQ = 4 TAD)



REGISTER 23-4: COMSTAT: COMMUNICATION STATUS REGISTER

Mode 0	R/C-0	R/C-0	R-0	R-0	R-0	R-0	R-0	R-0
	RXB0OVFL	RXB1OVFL	TXBO	TXBP	RXBP	TXWARN	RXWARN	EWARN
Mode 1	R/C-0	R/C-0	R-0	R-0	R-0	R-0	R-0	R-0
	—	RXBnOVFL	TXB0	TXBP	RXBP	TXWARN	RXWARN	EWARN
Mode 2	R/C-0	R/C-0	R-0	R-0	R-0	R-0	R-0	R-0
	$\overline{\text{FIFOEMPTY}}$	RXBnOVFL	TXBO	TXBP	RXBP	TXWARN	RXWARN	EWARN
	bit 7							bit 0

Legend:			
R = Readable bit	C = Clearable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 Mode 0:
RXB0OVFL: Receive Buffer 0 Overflow bit
1 = Receive Buffer 0 overflowed
0 = Receive Buffer 0 has not overflowed
Mode 1:
Unimplemented: Read as ‘0’
Mode 2:
$\overline{\text{FIFOEMPTY}}$: FIFO Not Empty bit
1 = Receive FIFO is not empty
0 = Receive FIFO is empty

bit 6 Mode 0:
RXB1OVFL: Receive Buffer 1 Overflow bit
1 = Receive Buffer 1 overflowed
0 = Receive Buffer 1 has not overflowed
Mode 1, 2:
RXBnOVFL: Receive Buffer n Overflow bit
1 = Receive Buffer n has overflowed
0 = Receive Buffer n has not overflowed

bit 5 **TXBO:** Transmitter Bus-Off bit
1 = Transmit error counter > 255
0 = Transmit error counter ≤ 255

bit 4 **TXBP:** Transmitter Bus Passive bit
1 = Transmit error counter > 127
0 = Transmit error counter ≤ 127

bit 3 **RXBP:** Receiver Bus Passive bit
1 = Receive error counter > 127
0 = Receive error counter ≤ 127

bit 2 **TXWARN:** Transmitter Warning bit
1 = Transmit error counter > 95
0 = Transmit error counter ≤ 95

bit 1 **RXWARN:** Receiver Warning bit
1 = 127 ≥ Receive error counter > 95
0 = Receive error counter ≤ 95

bit 0 **EWARN:** Error Warning bit
This bit is a flag of the RXWARN and TXWARN bits.
1 = The RXWARN or the TXWARN bits are set
0 = Neither the RXWARN or the TXWARN bits are set

EXAMPLE 23-3: TRANSMITTING A CAN MESSAGE USING BANKED METHOD

```
; Need to transmit Standard Identifier message 123h using TXB0 buffer.
; To successfully transmit, CAN module must be either in Normal or Loopback mode.
; TXB0 buffer is not in access bank.  And since we want banked method, we need to make sure
; that correct bank is selected.
BANKSEL  TXB0CON                    ; One BANKSEL in beginning will make sure that we are
                                    ; in correct bank for rest of the buffer access.
; Now load transmit data into TXB0 buffer.
MOVLW    MY_DATA_BYTE1              ; Load first data byte into buffer
MOVWF    TXB0D0                     ; Compiler will automatically set "BANKED" bit
; Load rest of data bytes - up to 8 bytes into TXB0 buffer.
...
; Load message identifier
MOVLW    60H                        ; Load SID2:SID0, EXIDE = 0
MOVWF    TXB0SIDL
MOVLW    24H                        ; Load SID10:SID3
MOVWF    TXB0SIDH
; No need to load TXB0EIDL:TXB0EIDH, as we are transmitting Standard Identifier Message only.

; Now that all data bytes are loaded, mark it for transmission.
MOVLW    B'00001000'                ; Normal priority; Request transmission
MOVWF    TXB0CON

; If required, wait for message to get transmitted
BTFSC    TXB0CON, TXREQ             ; Is it transmitted?
BRA      $-2                        ; No.  Continue to wait...

; Message is transmitted.
```

REGISTER 23-50: MSEL2: MASK SELECT REGISTER 2(1)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
FIL11_1	FIL11_0	FIL10_1	FIL10_0	FIL9_1	FIL9_0	FIL8_1	FIL8_0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **FIL11_1:FIL11_0:** Filter 11 Select bits 1 and 0
11 = No mask
10 = Filter 15
01 = Acceptance Mask 1
00 = Acceptance Mask 0

bit 5-4 **FIL10_1:FIL10_0:** Filter 10 Select bits 1 and 0
11 = No mask
10 = Filter 15
01 = Acceptance Mask 1
00 = Acceptance Mask 0

bit 3-2 **FIL9_1:FIL9_0:** Filter 9 Select bits 1 and 0
11 = No mask
10 = Filter 15
01 = Acceptance Mask 1
00 = Acceptance Mask 0

bit 1-0 **FIL8_1:FIL8_0:** Filter 8 Select bits 1 and 0
11 = No mask
10 = Filter 15
01 = Acceptance Mask 1
00 = Acceptance Mask 0

Note 1: This register is available in Mode 1 and 2 only.

TABLE 23-1: CAN CONTROLLER REGISTER MAP (CONTINUED)

Address[1]	Name	Address	Name	Address	Name	Address	Name
EFFh	—[4]	EDFh	—[4]	EBFh	—[4]	E9Fh	—[4]
EFEh	—[4]	EDEh	—[4]	EBEh	—[4]	E9Eh	—[4]
EFDh	—[4]	EDDh	—[4]	EBDh	—[4]	E9Dh	—[4]
EFCh	—[4]	EDCh	—[4]	EBCh	—[4]	E9Ch	—[4]
EFBh	—[4]	EDBh	—[4]	EBBh	—[4]	E9Bh	—[4]
EFAh	—[4]	EDAh	—[4]	EBAh	—[4]	E9Ah	—[4]
EF9h	—[4]	ED9h	—[4]	EB9h	—[4]	E99h	—[4]
EF8h	—[4]	ED8h	—[4]	EB8h	—[4]	E98h	—[4]
EF7h	—[4]	ED7h	—[4]	EB7h	—[4]	E97h	—[4]
EF6h	—[4]	ED6h	—[4]	EB6h	—[4]	E96h	—[4]
EF5h	—[4]	ED5h	—[4]	EB5h	—[4]	E95h	—[4]
EF4h	—[4]	ED4h	—[4]	EB4h	—[4]	E94h	—[4]
EF3h	—[4]	ED3h	—[4]	EB3h	—[4]	E93h	—[4]
EF2h	—[4]	ED2h	—[4]	EB2h	—[4]	E92h	—[4]
EF1h	—[4]	ED1h	—[4]	EB1h	—[4]	E91h	—[4]
EF0h	—[4]	ED0h	—[4]	EB0h	—[4]	E90h	—[4]
EEFh	—[4]	ECFh	—[4]	EAFh	—[4]	E8Fh	—[4]
EEEh	—[4]	ECEh	—[4]	EAEh	—[4]	E8Eh	—[4]
EEDh	—[4]	ECDh	—[4]	EADh	—[4]	E8Dh	—[4]
EECh	—[4]	ECCh	—[4]	EACh	—[4]	E8Ch	—[4]
EEBh	—[4]	ECBh	—[4]	EABh	—[4]	E8Bh	—[4]
EEAh	—[4]	ECAh	—[4]	EAAh	—[4]	E8Ah	—[4]
EE9h	—[4]	EC9h	—[4]	EA9h	—[4]	E89h	—[4]
EE8h	—[4]	EC8h	—[4]	EA8h	—[4]	E88h	—[4]
EE7h	—[4]	EC7h	—[4]	EA7h	—[4]	E87h	—[4]
EE6h	—[4]	EC6h	—[4]	EA6h	—[4]	E86h	—[4]
EE5h	—[4]	EC5h	—[4]	EA5h	—[4]	E85h	—[4]
EE4h	—[4]	EC4h	—[4]	EA4h	—[4]	E84h	—[4]
EE3h	—[4]	EC3h	—[4]	EA3h	—[4]	E83h	—[4]
EE2h	—[4]	EC2h	—[4]	EA2h	—[4]	E82h	—[4]
EE1h	—[4]	EC1h	—[4]	EA1h	—[4]	E81h	—[4]
EE0h	—[4]	EC0h	—[4]	EA0h	—[4]	E80h	—[4]

Note 1: Shaded registers are available in Access Bank low area, while the rest are available in Bank 15.

2: CANSTAT register is repeated in these locations to simplify application firmware. Unique names are given for each instance of the controller register due to the Microchip header file requirement.

3: These registers are not CAN registers.

4: Unimplemented registers are read as '0'.

REGISTER 24-12: DEVID1: DEVICE ID REGISTER 1 FOR PIC18F2682/2685/4682/4685

R	R	R	R	R	R	R	R
DEV2	DEV1	DEV0	REV4	REV3	REV2	REV1	REV0
bit 7							bit 0

Legend:		
R = Read-only bit	P = Programmable bit	U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed		u = Unchanged from programmed state

bit 7-5 **DEV2:DEV0:** Device ID bits
000 = PIC18F2682
001 = PIC18F2685
010 = PIC18F4682
011 = PIC18F4685

bit 4-0 **REV3:REV0:** Revision ID bits
These bits are used to indicate the device revision.

REGISTER 24-13: DEVID2: DEVICE ID REGISTER 2 FOR PIC18F2682/2685/4682/4685

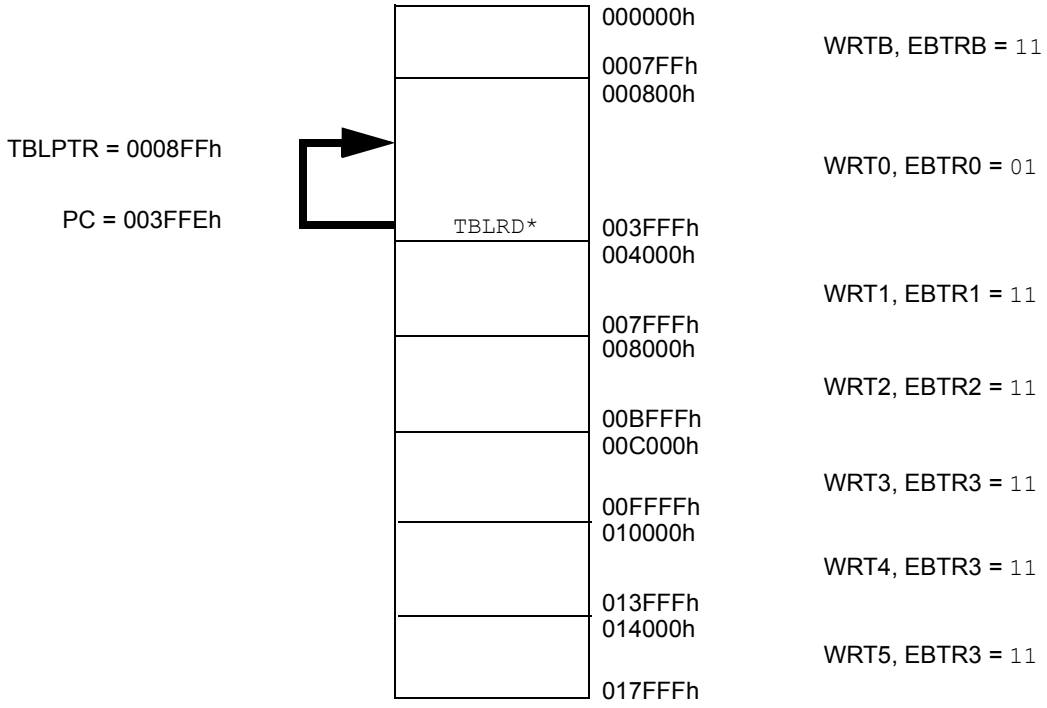
R	R	R	R	R	R	R	R
DEV10	DEV9	DEV8	DEV7	DEV6	DEV5	DEV4	DEV3
bit 7							bit 0

Legend:		
R = Read-only bit	P = Programmable bit	U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed		u = Unchanged from programmed state

bit 7-0 **DEV10:DEV3:** Device ID bits
These bits are used with the DEV2:DEV0 bits in Device ID Register 1 to identify the part number.
0010 0111 = PIC18F2682/2685/4682/4685 devices

Note 1: These values for DEV10:DEV3 may be shared with other devices. The specific device is always identified by using the entire DEV10:DEV0 bit sequence.

FIGURE 24-8: EXTERNAL BLOCK TABLE READ (EBTRn) ALLOWED



Results: Table reads permitted within Blockn, even when EBTRBn = 0.
TABLAT register returns the value of the data at the location TBLPTR.

27.2 DC Characteristics: Power-Down and Supply Current PIC18F2682/2685/4682/4685 (Industrial) PIC18LF2682/2685/4682/4685 (Industrial) (Continued)

PIC18LF2682/2685/4682/4685 (Industrial)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC18F2682/2685/4682/4685 (Industrial, Extended)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**		
	Supply Current (IDD)(2,3)						
	PIC18LF268X/468X	15	36	µA	-40°C	VDD = 2.0V	FOSC = 31 kHz (**RC_RUN** mode, Internal oscillator source)
		15	36	µA	+25°C		
		15	36	µA	+85°C		
	PIC18LF268X/468X	40	100	µA	-40°C	VDD = 3.0V	
		35	100	µA	+25°C		
		30	100	µA	+85°C		
	All devices	105	200	µA	-40°C	VDD = 5.0V	
		90	200	µA	+25°C		
		80	200	µA	+85°C		
	Extended devices only	80	200	µA	+125°C		
	PIC18LF268X/468X	0.32	1	mA	-40°C	VDD = 2.0V	FOSC = 1 MHz (**RC_RUN** mode, Internal oscillator source)
		0.33	1	mA	+25°C		
		0.33	1	mA	+85°C		
	PIC18LF268X/468X	0.6	1.6	mA	-40°C	VDD = 3.0V	
		0.55	1.6	mA	+25°C		
		0.6	1.6	mA	+85°C		
	All devices	1.1	3	mA	-40°C	VDD = 5.0V	
		1.1	3	mA	+25°C		
		1	3	mA	+85°C		
	Extended devices only	1	3	mA	+125°C		
	PIC18LF268X/468X	0.8	2.2	mA	-40°C	VDD = 2.0V	FOSC = 4 MHz (**RC_RUN** mode, Internal oscillator source)
		0.8	2.2	mA	+25°C		
		0.8	2.2	mA	+85°C		
	PIC18LF268X/468X	1.3	3	mA	-40°C	VDD = 3.0V	
		1.3	3	mA	+25°C		
		1.3	3	mA	+85°C		
	All devices	2.5	5.3	mA	-40°C	VDD = 5.0V	
		2.5	5.3	mA	+25°C		
		2.5	5.3	mA	+85°C		
	Extended devices only	2.5	8	mA	+125°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD;
MCLR = VDD; WDT enabled/disabled as specified.

3: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kΩ.

4: Standard low-cost 32 kHz crystals have an operating temperature range of -10°C to +70°C. Extended temperature crystals are available at a much higher cost.

27.4 AC (Timing) Characteristics

27.4.1 TIMING PARAMETER SYMBOLOGY

The timing parameter symbols have been created using one of the following formats:

1. TppS2ppS
2. TppS
3. TCC:ST (I^2C specifications only)
4. Ts (I^2C specifications only)

T			
F	Frequency	T	Time

Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	OSC1
ck	CLKO	rd	$\overline{RD}$
cs	$\overline{CS}$	rw	$\overline{RD}$ or $\overline{WR}$
di	SDI	sc	SCK
do	SDO	ss	$\overline{SS}$
dt	Data in	t0	T0CKI
io	I/O port	t1	T13CKI
mc	$\overline{MCLR}$	wr	$\overline{WR}$

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (High-Impedance)	V	Valid
L	Low	Z	High-Impedance
I^2C only			
AA	output access	High	High
BUF	Bus free	Low	Low

TCC:ST (I^2C specifications only)

CC			
HD	Hold	SU	Setup
ST			
DAT	DATA input hold	STO	Stop condition
STA	Start condition		

TABLE 27-21: MASTER SSP I²C™ BUS DATA REQUIREMENTS

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
100	THIGH	Clock High Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
101	TLOW	Clock Low Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
102	TR	SDA and SCL Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	300	ns	
103	TF	SDA and SCL Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	100	ns	
90	TSU:STA	Start Condition Setup Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	Only relevant for Repeated Start condition
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
91	THD:STA	Start Condition Hold Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	After this period, the first clock pulse is generated
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
106	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	ms	
107	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
92	TSU:STO	Stop Condition Setup Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
109	TAA	Output Valid from Clock	100 kHz mode	—	3500	ns	
			400 kHz mode	—	1000	ns	
			1 MHz mode(1)	—	—	ns	
110	TBUF	Bus Free Time	100 kHz mode	4.7	—	ms	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	ms	
D102	CB	Bus Capacitive Loading		—	400	pF	

Note 1: Maximum pin capacitance = 10 pF for all I²C pins.

2: A Fast mode I²C™ bus device can be used in a Standard mode I²C bus system, but parameter 107 ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line, parameter 102 + parameter 107 = 1000 + 250 = 1250 ns (for 100 kHz mode), before the SCL line is released.

APPENDIX C: CONVERSION CONSIDERATIONS

This appendix discusses the considerations for converting from previous versions of a device to the ones listed in this data sheet. Typically, these changes are due to the differences in the process technology used. An example of this type of conversion is from a PIC16C74A to a PIC16C74B.

Not Applicable

APPENDIX D: MIGRATION FROM BASELINE TO ENHANCED DEVICES

This section discusses how to migrate from a Baseline device (i.e., PIC16C5X) to an Enhanced MCU device (i.e., PIC18FXXX).

The following are the list of modifications over the PIC16C5X microcontroller family:

Not Currently Available